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Part Number: [0786463001](#)
Status: **Active**
Overview: SD and SIM Memory Card Sockets
Description: micro-SIM Card Socket without Detect Switch, 1.45mm Height, Push-Pull Eject, Surface Mount, 6 Circuits, Low-Halogen, Lead-Free

Documents:

[3D Model](#) [Product Specification PS-78646-001-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[3D Model \(PDF\)](#)

General

Product Family	Memory Card Sockets
Series	78646
Overview	SD and SIM Memory Card Sockets
Product Name	micro-SIM
Style	Push-Pull
UPC	884982798830

Physical

Card Detection Switch	No
Card Entry Location	Front
Circuits (Loaded)	6
Circuits (maximum)	6
Durability (mating cycles max)	1500
Ejector Button Side	N/A
Material - Contact	Copper Alloy
Material - Plating Mating	Gold
Material - Shell	Stainless Steel
Net Weight	0.243/g
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface	1.27mm
Temperature Range - Operating	-30° to +85°C
Termination Interface: Style	Surface Mount

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	15V DC

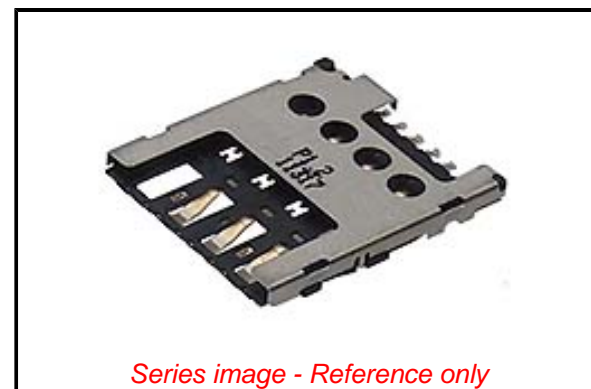
Solder Process Data

Duration at Max. Process Temperature (seconds)	010
Lead-freeProcess Capability	REFLOW
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Electrical Model Document	EE-78646-001-001
Product Specification	PS-78646-001-001
Sales Drawing	SD-78646-001-001



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
D(2020)9139-DC (19
Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

China RoHS

Green Image

Not Relevant

Not Contained

Search Parts in this Series

[78646 Series](#)

Mates With

micro-SIM Card



PRODUCT SPECIFICATION

MICRO SIM CARD CONNECTOR, 1.45mm HEIGHT, PUSH-PULL

1.0 SCOPE

This Product Specification covers the performance requirements of the Micro SIM CardConnector

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Product Name

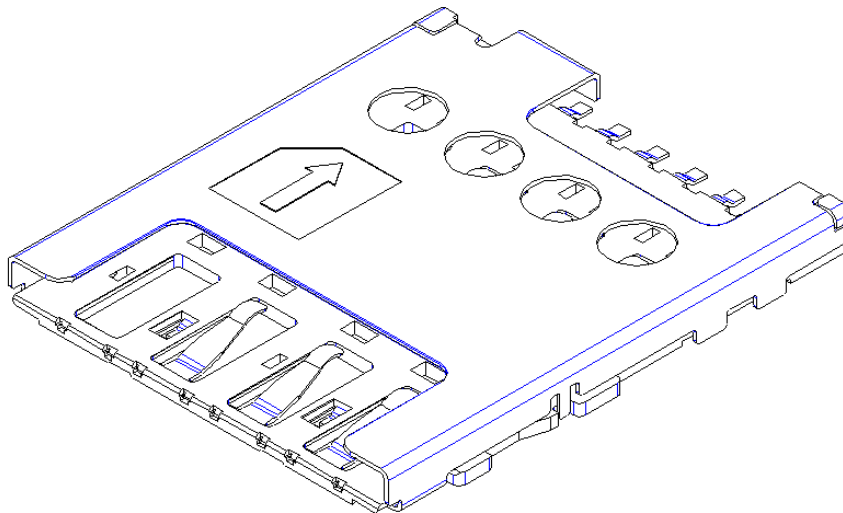
Part Number

MICRO SIM CARD CONNECTOR, 1.45MM HEIGHT, PUSH-PULL

78646

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See Sales Drawing SD-78646-001for information on dimensions, materials, platings and markings.



TENTATIVE RELEASE:

THIS SPECIFICATION IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. PRELIMINARY TEST DATA MAY EXIST, BUT THIS SPECIFICATION IS SUBJECTED TO CHANGE BASED ON THE RESULTS OF ADDITIONAL TESTING AND EVALUATION.

<u>REVISION:</u> 2	<u>ECR/ECN INFORMATION:</u> EC No: S2013-0167 DATE: 2012/10/11	<u>TITLE:</u> MICRO SIM CARD CONNECTOR, 1.45mm HEIGHT, PUSH-PULL	<u>SHEET No.</u> 1 of 10
<u>DOCUMENT NUMBER:</u> PS-78646-001	<u>CREATED / REVISED BY:</u> JTAN 2012/10/11	<u>CHECKED BY:</u> FCSOO 2012/10/11	<u>APPROVED BY:</u> KHLIM 2012/10/11



PRODUCT SPECIFICATION

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents form a part of this specification to the extended specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence.

4.0 RATINGS

4.1 CURRENT RATING

0.5Amps Max. per contact

4.2 VOLTAGE RATING

15 Volt DC Max.

4.3 TEMPERATURE

Operating: - 30°C to + 85°C
Storage (with packaging): - 5°C to + 85°C

5.0 MECHANICAL INTERFACE

5.1 CARD INTERFACE

SIM card interface: GSM 11.11 specification

5.2 PWB INTERFACE

Plating on PWB pads: OSP plated copper

6.0 PERFORMANCE

6.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Low Level Contact Resistance (LLCR)	Mate connectors with dry circuit (20 mV, 100mA MAX) at 0.60mm away from housing top surface (see appendix 1) (IEC 60512-2-1)	100 milliohm [MAXIMUM] [initial] Value includes bulk resistance of terminal
2	Insulation Resistance	Unmated connectors: apply a voltage of 500 VDC between adjacent contact for 1 minutes (IEC 60512-3-1)	1000 Megohms [MINIMUM]

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3	Dielectric Withstanding Voltage	Unmated connectors: apply a voltage of 500VAC between adjacent contact for 1 minutes (IEC 60512-3-1)	No voltage breakdown
4	Temperature Rise	Mated and measure the temperature rise of contact, when rated current is passed. (IEC 60512-5-1)	Temperature Rise +30°C [MAXIMUM]

6.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Contact Normal Force	Apply a perpendicular force to the contact at the rate of 12.5mm/min. The min. deflection of contact is 0.27mm from surface of housing. (Refer to Appendix 2). Note : a) All forces to be measured at returned curve. b) Force to be taken after 3X reflow.	0.20N min at minimum deflection
6	Durability (Life Cycle)	Mate connectors 2.54cm/min to 1500 cycles. Horizontal insertion for max deflection case.	Contact resistance 100 milliohms [MAXIMUM] No mechanical damage
7	Card Insertion Force	Insert the card in mating direction at a Max. rate of 12.5 mm/min	6N [MAXIMUM]
8	Card Withdrawal Force	Withdraw the card in un-mating direction at a rate of 12.5 mm/min	0.50N [MINIMUM]
9	Solder Joint Peeling Strength	Apply a load to the connector parallel to the PWB (refer to Appendix 1 on X & Y direction)	50 N [MINIMUM]

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PRODUCT SPECIFICATION

<p>10</p>	<p>Resistance to Soldering Heat</p>	<p>Unmated sample to be passed through reflow over according to temp profiles (shown in section 9.0) three times (Sequences: above PWB – under PWB – under PWB)</p>	<p>No damage to connector appearance No connector drop off from PWB</p>
<p>11</p>	<p>Solderability</p>	<p>Solder paste is deposited on a ceramic plate via stencil. The connector are steam aged & placed on a solder paste print. The substrate is processed through a forced hot convention oven. The connector are removed from the ceramic plate & inspected. Steam Aging : 8 hour (ANSI-J-STD 002)</p>	<p>No bridging & Good coverage</p>

6.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
<p>12</p>	<p>Dry cold (steady state)</p>	<p>At -40°C for 96 hours Recovery: 2 hours at ambient atmosphere (IEC60068-2-1Ab)</p>	<p>No mechanical damage Contact resistance 100 milliohms [MAXIMUM]</p>
<p>13</p>	<p>Dry heat (steady state)</p>	<p>At +85°C for 96 hours Recovery: 2 hours at ambient atmosphere (IEC60068-2-2Bb)</p>	<p>No mechanical damage Contact resistance 100 milliohms [MAXIMUM]</p>
<p>14</p>	<p>Thermal Shock</p>	<p>25 cycles at Ta = -55°C for 0.5 hours, then change of temp = 25°C MAX 5min, then, Tb = +85°C for 0.5hour, then cool to ambient Recovery: 2hours at ambient atmosphere (IEC60068-2-14 Test Na)</p>	<p>No mechanical damage Contact resistance 100 milliohms [MAXIMUM]</p>

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PRODUCT SPECIFICATION

15	Vibration (Random)	Frequency: 10~100 Hz, 0.0132 g ² /Hz; Frequency: 100~500Hz, -3dB/Oct Applied for 1 hours in X, Y and Z axis in minimum deflection position.	No mechanical damage Contact resistance 100 milliohms [MAXIMUM] Discontinuity < 1 μs
16	Damp Heat (Cyclic)	Temp 25-55°C and 95-100%RH for 18 cycles of 24hours. Recovery at 25°C and 75%RH for 2hours. (Typical cycle in temp 25°C → 55°C in 3 hours; then maintain at 55°C for 9hours; temp 55°C → 25°C in 3 hours; then maintain at 25°C for 9hours) (IEC60068-2-30Db)	No mechanical damage Contact resistance 100 ohms [MAXIMUM] Insulation resistance 1000 milliohms [MINIMUM]
17	Shock (specified pulse)	Pulse shape = half sine Peak acceleration = 490m/s ² (50G) Duration of pulse = 11ms Apply 3 successive shocks in each direction along the 3 mutually perpendicular axes. (IE-C60068-2-27Ea)	No mechanical damage Contact resistance 100 milliohms [MAXIMUM] Discontinuity < 1 μs

7.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. The parts shall be carried in reels inside boxes.

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PRODUCT SPECIFICATION

8.0 TEST SEQUENCES

Test Group →	Group 1	Group 2	Group 3	Group 4	Group 5	Group 6	Group 7
Test or Examination ↓							
Sample size	5	5	5	5	5	5	5
Examination of connector(s)	1	1	1	1	1	1	1
Contact Resistance	2,4,6,8			2,5	2,4,6		
Insulation Resistance		3,6					
Dielectric Withstanding Voltage		2,7					
Temperature Rise			2				
Contact Normal Force							
Durability (Life Cycle)	3						
Solder Joint Peeling Strength (X & Y axis)						3	
Dry Cold					3		
Dry Heat					5		
Thermal Shock	5	4					
Damp Heat (cyclic)	7	5					
Vibration				3			
Shock				4			
Solderability							2
Resistance to Soldering Heat						2	

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PRODUCT SPECIFICATION

Screen Test Group →	Group 1	Group 2	Group 3	Group 4
Test or Examination ↓				
Sample size	5	5	5	5
Appearance	1	1	1	1
Resistance to Soldering Conditions	2	2		
Contact Resistance	3,8			
Insulation Resistance		3,6		
Dielectric Withstanding Voltage		4,7		
Contact Normal Force	4,9			
Durability (Life Cycle)	7	5		
Solder Joint Peeling Strength				2
Solderability			2	
Card Insertion Force	5,10			
Card Withdrawal Force	6,11			

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PRODUCT SPECIFICATION

9.0 SOLDERING PROFILE

Pb-free reflow profile requirement for solderability testing

The reflow profile defined in this section describes expected minimum reflow profile. Temperature measured on solderable termination or on top of component.

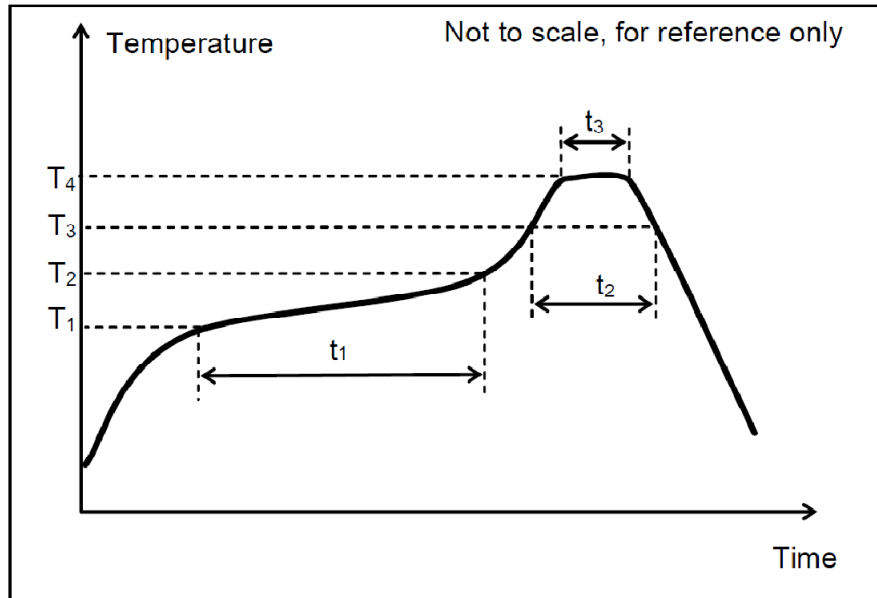


Figure 1. Reflow profile for solderability testing.

Pb-free reflow profile requirements for solderability testing		
Parameter	Reference	Specification
Preheat minimum temperature	T ₁	150°C
Preheat maximum temperature	T ₂	180°C
Preheat time	t ₁	60...120 s
Time above 217°C	t ₂	Max 30 sec
Peak temperature in reflow	T ₄	230°C (-0/+5°C)
Time at peak temperature	t ₃	10 s
Temperature gradient in cooling		Max -5°C/s

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PRODUCT SPECIFICATION

Reflow soldering profile for soldering heat resistance testing

The reflow profile specified in this section describes expected maximum heat exposure of components during the reflow process .

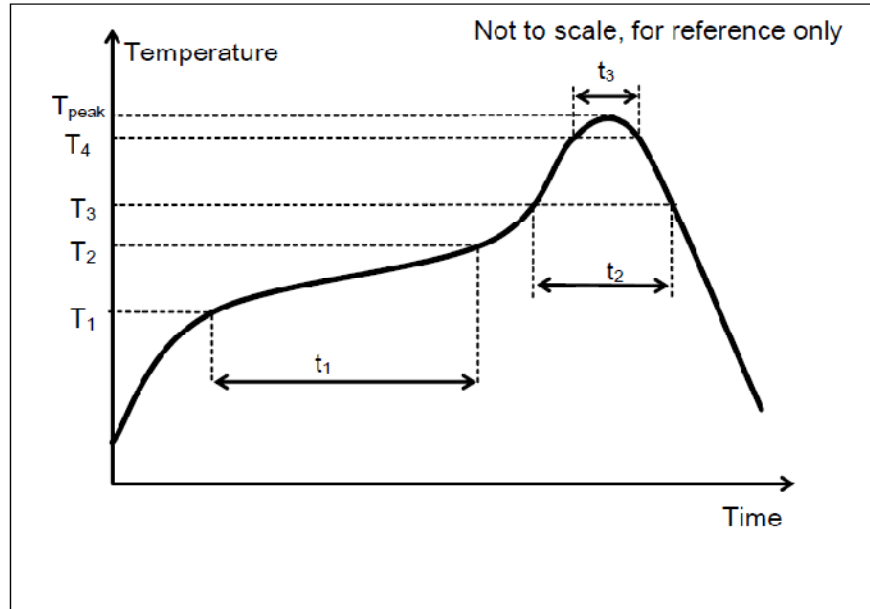


Figure 2. Reflow profile for soldering heat resistance testing.

Pb-free reflow profile requirements for soldering heat resistance		
Parameter	Reference	Specification
Preheat minimum temperature	T ₁	150°C
Preheat maximum temperature	T ₂	180°C
Preheat time	t ₁	120...180 s
Time above 217°C (T ₃)	t ₂	Min 65 s
Time above 250°C (T ₄)	t ₃	Min10 s
Peak temperature in reflow	T _{peak}	255°C (-0/+5°C)
Temperature gradient in cooling		Max -5°C/s
Time from 40°C to 220°C		Min. 200 s

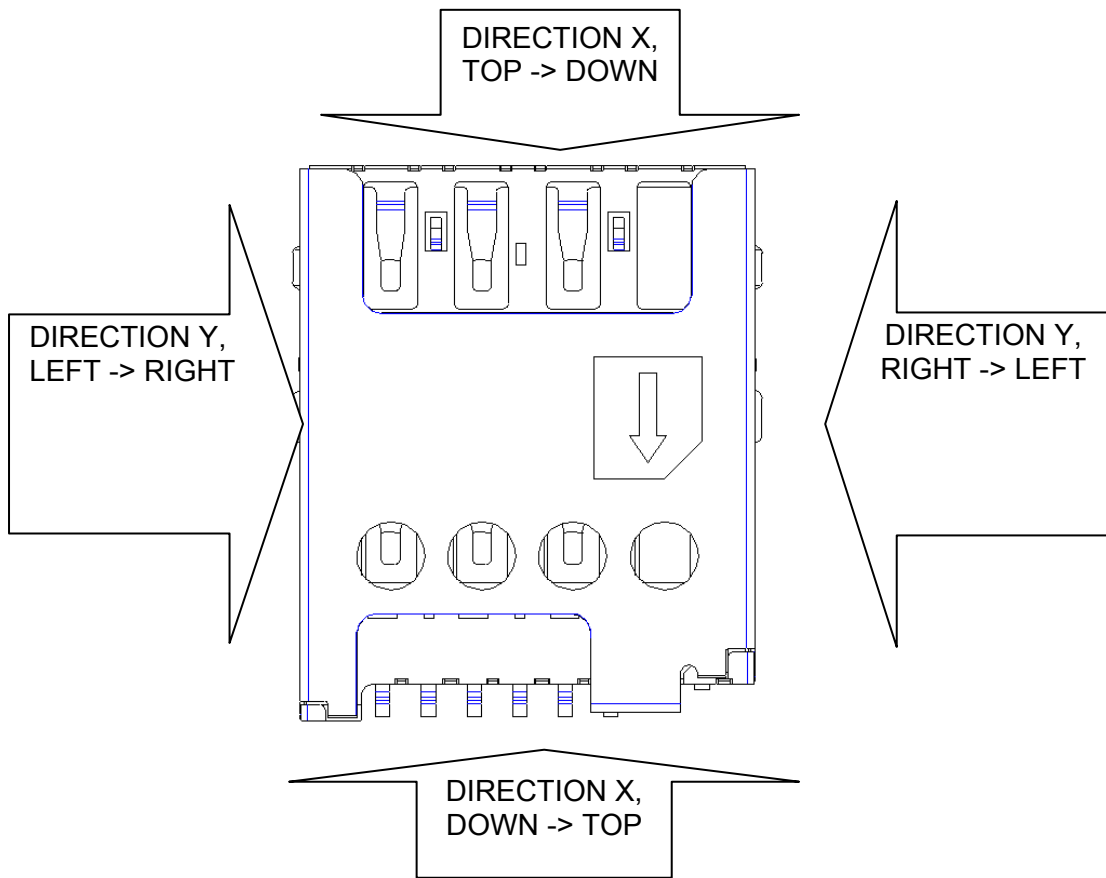
REVISION: 2	ECR/ECN INFORMATION: EC No: S2013-0167 DATE: 2012/10/11	TITLE: MICRO SIM CARD CONNECTOR, 1.45mm HEIGHT, PUSH-PULL	SHEET No. 9 of 10
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PRODUCT SPECIFICATION

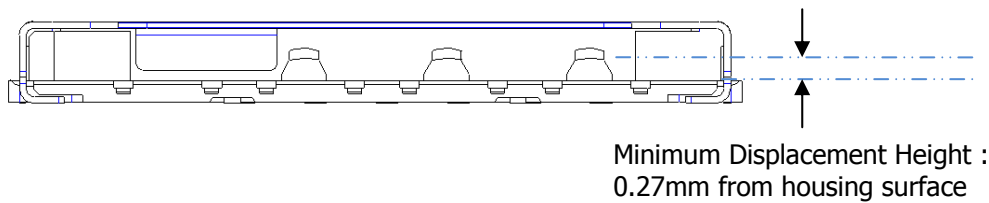
APPENDIX 1 :

Solder Joint Peel Strength Pushing Direction

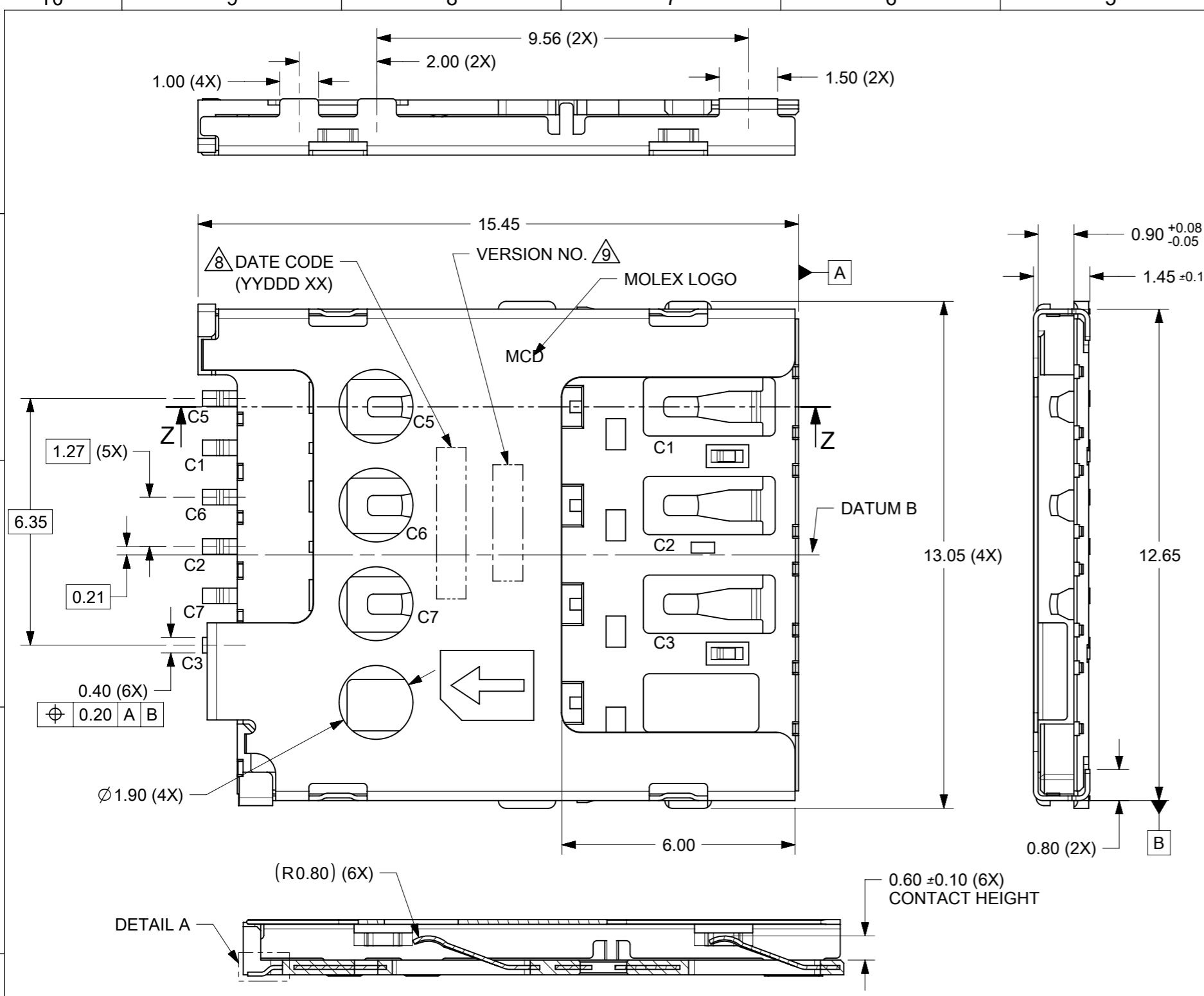


APPENDIX 2 :

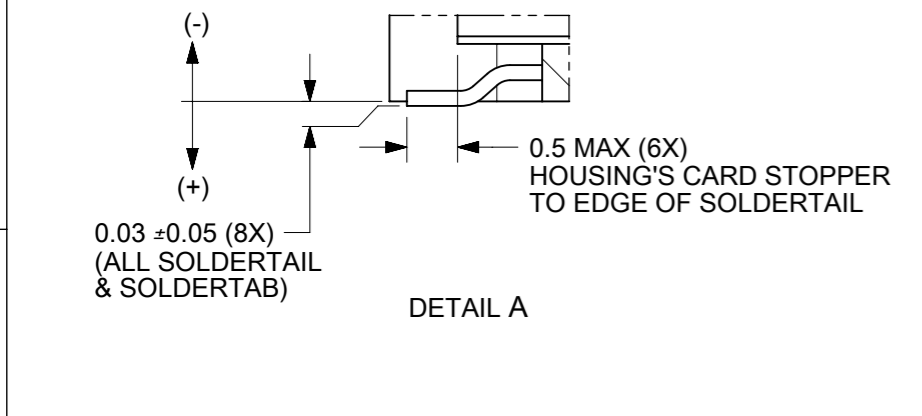
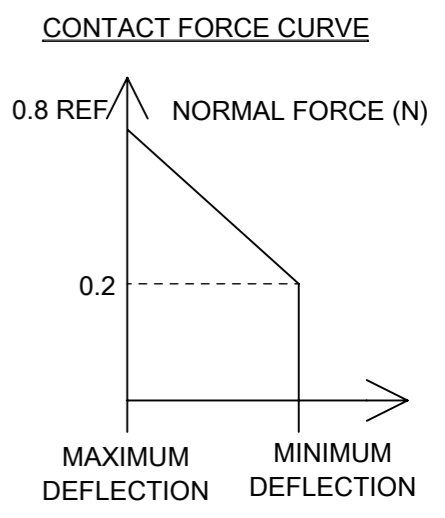
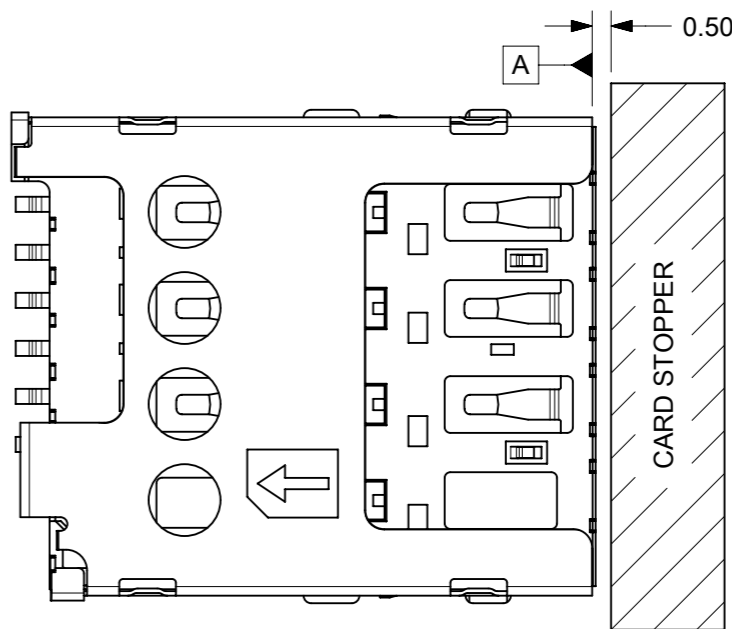
Minimum Displacement Height



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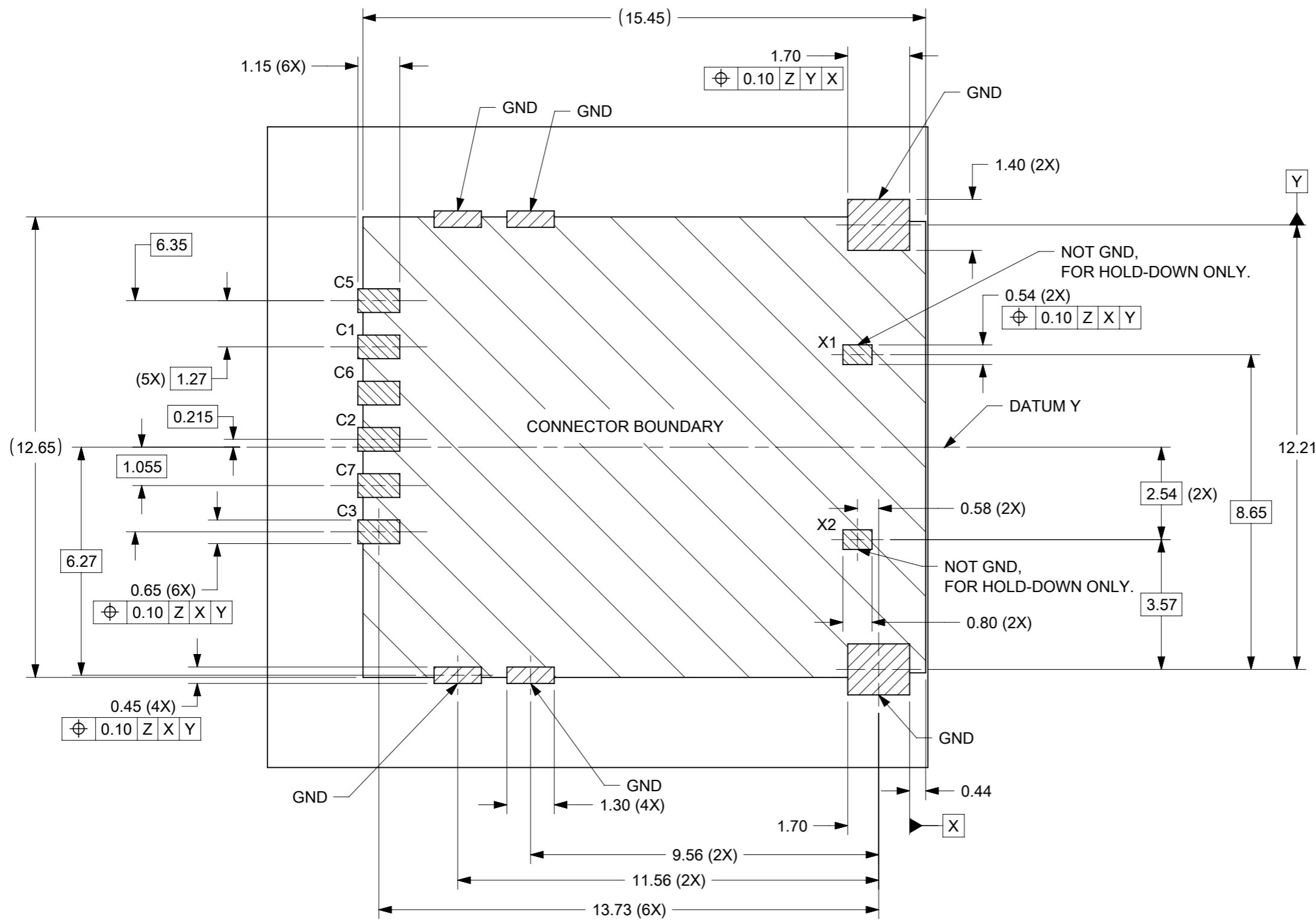


- NOTE:
- MATERIAL: HOUSING : LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94-V0, COLOR: BLACK
 TERMINAL : COPPER ALLOY
 METAL SHELL : STAINLESS STEEL
 - FINISH:
 TERMINAL:-
 CONTACT : SEE TABLE.
 SOLDERTAIL: 1.27µm MIN. MATTE TIN OVER 1.27µm NICKEL UNDERPLATE.
 SHELL :-
 SOLDERTAB : 1.27µm MIN. MATTE TIN OVER 1.27µm NICKEL UNDERPLATE.
 TOP SURFACE : 1.27µm NICKEL PLATING.
 - OVERALL (SOLDERTAIL & SOLDERTAB) COPLANARITY 0.08mm, MAX.
 - ALLOWABLE SIM CARD SLIDE OUT W.R.T. DATUM A : 1.00mm MAX.
 - PRODUCT SPECIFICATION: PS-78646-001
 - PACKAGING SPECIFICATION: RPK-78646-001
 - COMPLIANT TO RoHS DIRECTIVE 2011/65/EU AND ELV DIRECTIVE 2000/53/EC.
- △8 DATE CODE: YY DDD XX
 YEAR DAY LINE 1/2/3
 SHIFT: D - DAY
 N - NIGHT
- △9 VERSION NO: V1.3



PART NO.	PLATING AT CONTACT
786463001	0.38µm MIN. GOLD OVER 1.27µm NICKEL UNDERPLATE.
DOCUMENT STATUS	P1
RELEASE DATE	2020/08/06 00:20:56

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	CURRENT REV DESC:		molex
	△A = 0	mm	NTS	
DIVISIONAL SYMBOLS	△E = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		MICRO SIM CONNECTOR 1.45MM HEIGHT, PUSH PULL
	△F = 0	ANGULAR TOL ± 3.0°		PRODUCT CUSTOMER DRAWING
4 PLACES ±		EC NO: 628683	2020/06/30	DOCUMENT NUMBER
3 PLACES ±		DRWN: EZHANG06	2020/08/06	SD-78646-001
2 PLACES ± 0.2		CHK'D: AYIN	2020/08/06	DOC TYPE
1 PLACE ±		APPR: AYIN		DOC PART
0 PLACES ±		INITIAL REVISION:		REVISION
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRWN: JTAN02	2011/02/24	
THIRD ANGLE PROJECTION		APPR: KHLIM	2011/03/16	
DRAWING		SERIES		MATERIAL NUMBER
A3-SIZE		78646		CUSTOMER
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				GENERAL MARKET
				SHEET NUMBER
				1 OF 3

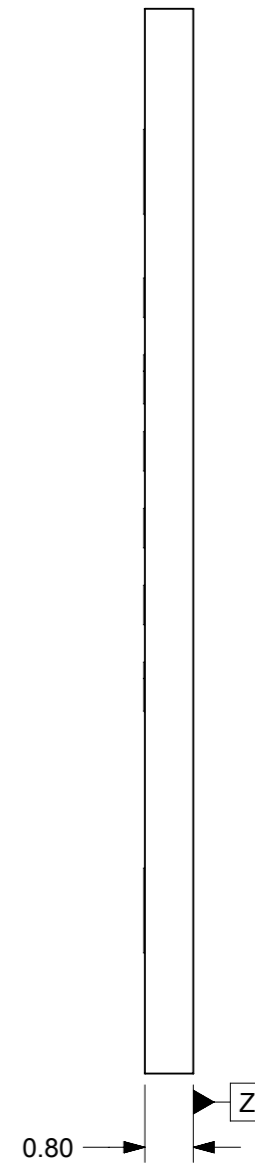


RECOMMENDED PCB LAYOUT
PWB TOLERANCE : ± 0.05mm

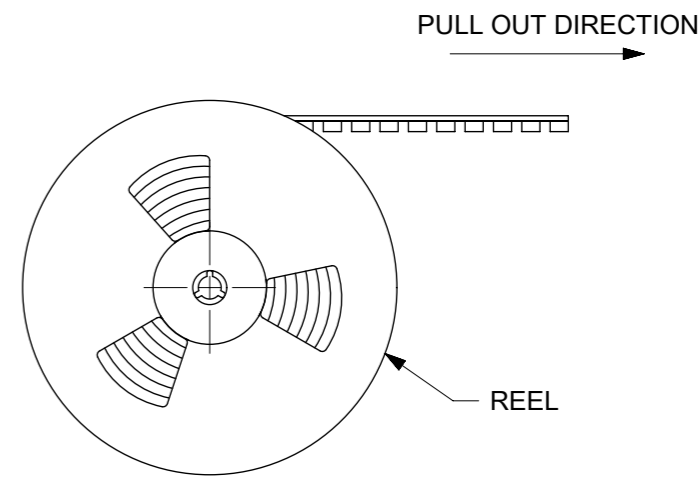
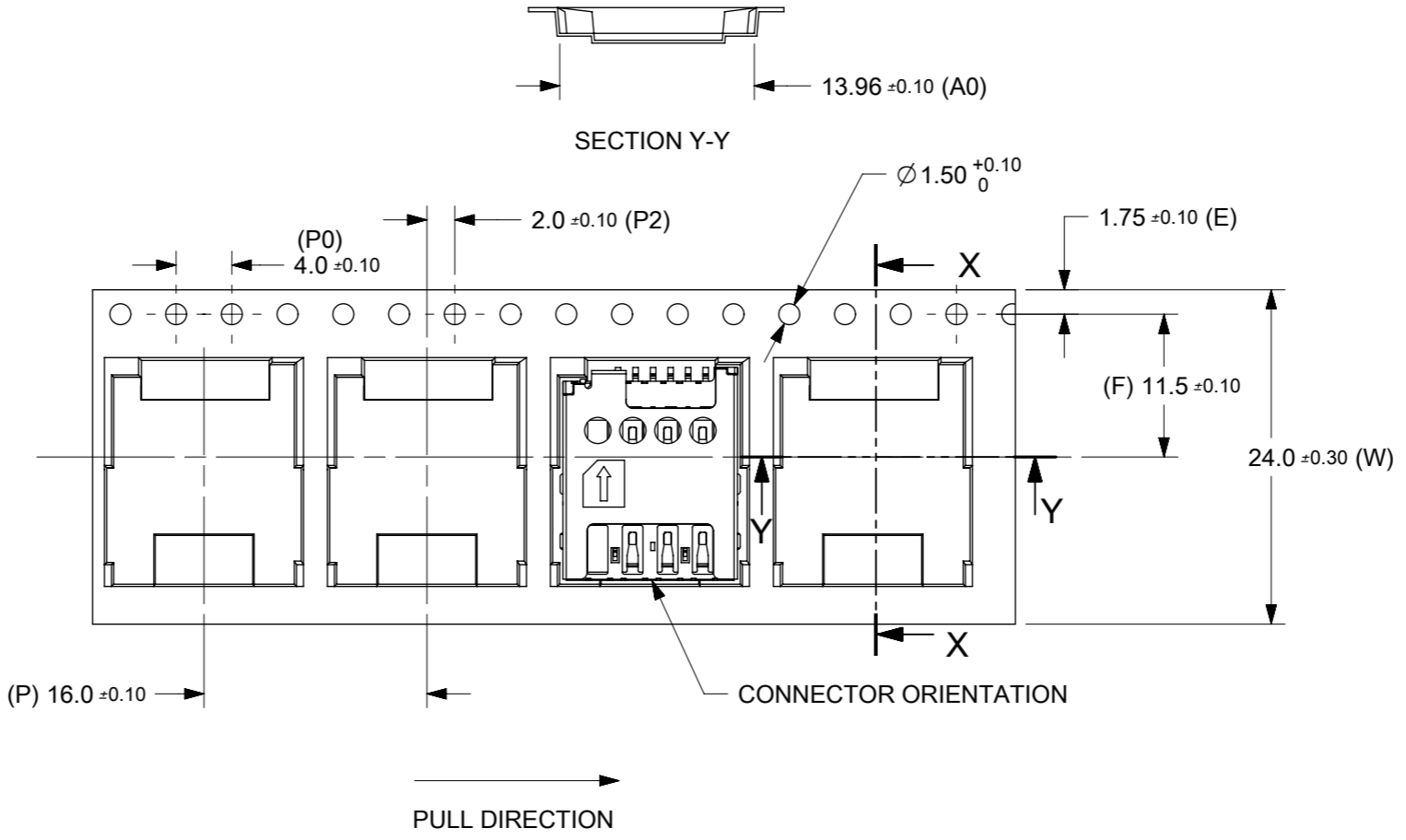
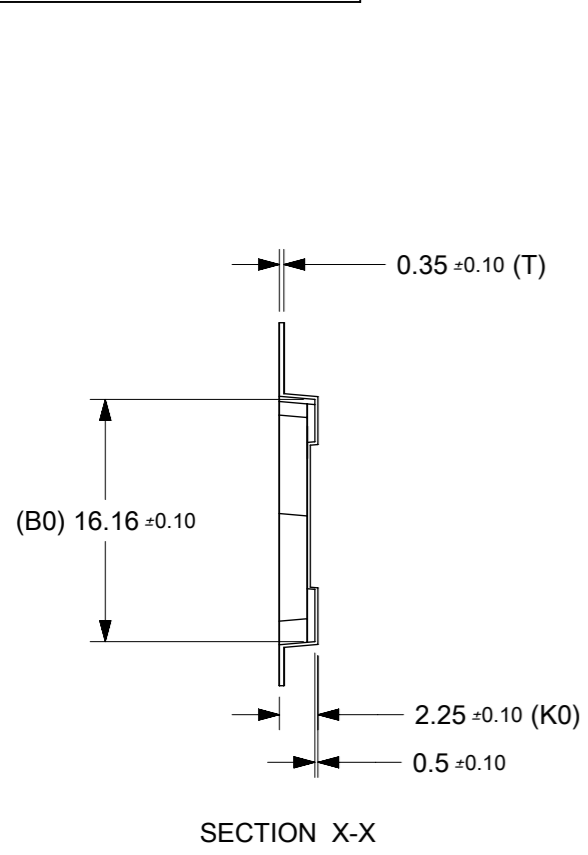
PIN NO.	ASSIGNMENT
C1	Vcc (SUPPLY VOLTAGE)
C2	RST (RESET SIGNAL)
C3	CLK (CLOCK SIGNAL)
C5	GND
C6	Vpp (VARIABLE SUPPLY VOLTAGE)
C7	I/O (DATA INPUT/OUTPUT)
X1	NOT GND, FOR HOLD DOWN ONLY. (NOTE:X1 IS LINKED TO C1)
X2	NOT GND, FOR HOLD DOWN ONLY. (NOTE:X2 IS LINKED TO C3)

DOCUMENT STATUS	P1	RELEASE DATE	2020/08/06	00:20:56
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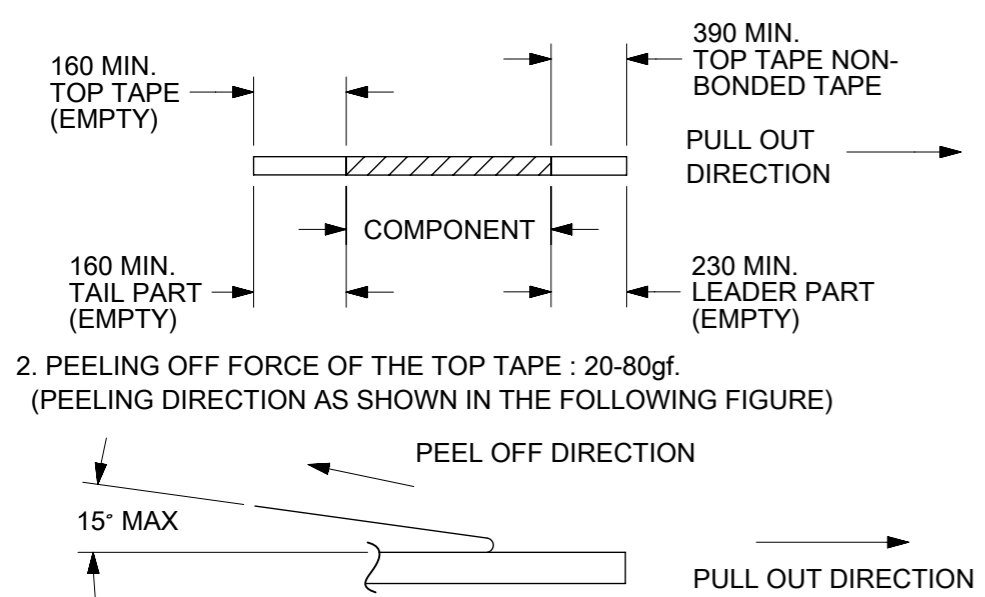
FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	CURRENT REV DESC:		molex																															
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FUNCTIONAL SYMBOLS	DIMENSION UNITS	SCALE																																	
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	0 PLACES	±																																	
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PACKAGING INFORMATION



NOTES :



- 3. TAPE & REEL SPECIFICATION IS AS PER EIA-481.
- 4. TAPE & REEL QTY. : 1500PCS / REEL.
- 5. THE TAPE IS TREATED FOR ANTI-STATIC.

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:		molex
	DIMENSION UNITS	SCALE			
▽A = 0	mm	NTS			MICRO SIM CONNECTOR 1.45MM HEIGHT, PUSH PULL
▽E = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)				PRODUCT CUSTOMER DRAWING
▽F = 0	ANGULAR TOL ± 3.0°				
DIVISIONAL SYMBOLS	4 PLACES	±	EC NO: 628683	2020/06/30	DOCUMENT NUMBER
	3 PLACES	±	DRWN: EZHANG06	2020/08/06	
	2 PLACES	± 0.2	CHK'D: AYIN	2020/08/06	DOC TYPE
	1 PLACE	±	APPR: AYIN	2020/08/06	DOC PART
	0 PLACES	±	INITIAL REVISION:		REVISION
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER
			A3-SIZE	78646	CUSTOMER
					SEE TABLE
					GENERAL MARKET
					SHEET NUMBER
					3 OF 3